

REMARKS

The amended claims, as set forth hereinabove, are being submitted concurrently with the filing of this application, in order to obviate the rejection of the previously filed claims in the final rejection of April 7, 2006. In particular, the claims have been rejected in failing to fully comply with the 35 U.S.C. §112, first paragraph, with the written description.

Furthermore, the claims have been rejected under 35 U.S.C. §103(a) as being unpatentable over Katchmar, previously cited, in view of the Admitted Prior Art and Barber, et al., as previously cited and as detailed in the Office Action.

Accordingly, in order to clearly and unambiguously obviate the rejection of the claims as being obvious in view of the prior art, while concurrently overcoming the formal ground of rejection, applicants have amended the claims to indicate that the electrically non-conductive adhesive extends into the proximity with the edges of the semiconductor chip, rather than with the heat spreader.

Furthermore, the claims have also been amended to incorporate the limitations of Claim 6 into Claim 1 and, respectively, Claim 16 into Claim 11.

The foregoing is deemed to clearly and patentably distinguish over the art, while meeting the requirements of the claim language conforming with the specification.

In particular, applicants note that the electrically-conductive adhesive only covers a small spot on the surface of the semiconductor chip and is essentially encompassed to a major extent by the large surfaced electrically non-conductive adhesive, so as to prevent any potential short circuiting of the electronic device. This has now been clearly emphasized in that the claims have been amended to indicate that the major surface portion of the semiconductor chip is covered by the electrically non-conductive adhesive, which extends

into proximity with the edges of the semiconductor chip. This should clearly provide the patentable distinctions, while conforming the claim language to the disclosure.

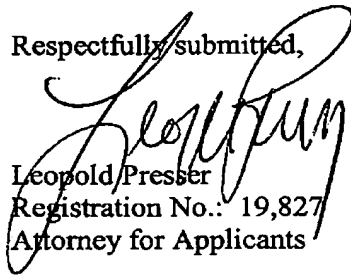
Reverting to the prior art publications, and particularly the primary reference of record, Katchmar, U.S. Patent No. 6,392,890 B1, discloses the electrically conductive adhesive being a small portion of the surface area. To the contrary, as shown in Katchmar, in all instances, the electrically-conductive adhesive portion or electrical conductor between the heat spreader and the semiconductor chip covers a major or large surface area of the semiconductor chip, with the electrically non-conductive adhesive surrounding the electrically-conductive adhesive being relatively a small portion of the surface area, particularly in comparison with the relatively large area defined by the electrically-conductive adhesive presently a danger of short-circuiting. This is clearly in contrast with the present invention, which confines the electrically conductive adhesive to a small spot on the surface of the semiconductor chip, substantially within the confines of the non-conductive adhesive so as to avoid the potential hazard of an electrical short-circuiting of the electronic device.

Also, the secondary prior art publication, as referred to by the Examiner, such as Barber, et al. and the state of the prior art discussed in the specification and Information Disclosure Statement by the applicants, fails to disclose the small spot, such as 1mm in diameter, which is located on the semiconductor chip and which is formed by the electrically-conductive adhesive and which is essentially surrounded by a large surface area of an electrically non-conductive adhesive. This provides significant advantages in the safety of manufacturing and employing the electronic device in operation.

Accordingly, applicants respectfully submit that the claims, as amended herein, are clearly and unambiguously directed to allowable and patentable subject matter, and the early and favorable consideration of the application on the merits and issuance of the Notice of Allowance by the Examiner is earnestly solicited.

However, in the event that the Examiner has any queries concerning the instantly submitted Amendment, applicants' attorney respectfully requests that he be accorded the courtesy of possibly a telephone conference to discuss any matters in need of attention.

Respectfully submitted,


Leopold Presser
Registration No.: 19,827
Attorney for Applicants

Scully, Scott, Murphy & Presser, P.C.
400 Garden City Plaza – Suite 300
Garden City, New York 11530
(516) 742-4343

LP:jy